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1674770 - 8 Product Details



1674770 -8

✓ Active

PGA Sockets

Always EU RoHS/ELV Compliant (Statement of Compliance

Product Highlights:

- ? Zero Insertion Force
- Number of Positions = 479
- PCB Mount Style = Surface Mount
- ? Grid Size = 26x26
- ? Grid Spacing = 1.27 x 1.27 mm

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Quick Links

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Documentation & Additional Information

Product Drawings:

 PACKING ASSY mPGA47X SOCKET LEAD FREE BALL (PDF, English)

Catalog Pages/Data Sheets:

None Available

Product Specifications:

mPGA SOCKET 479&478X (3H) CAM TYPE for Mobile PC (PDF, Japanese)

Application Specifications:

? None Available

Instruction Sheets:

mPGA Socket 479&478X (3H) CAM TYPE for Mobile PC (PDF, Japanese)

CAD Files: (CAD Format & Compression Information

- 2 2D Drawing (DXF, Version K)
- ? 3D Model (IGES, Version K)
- ? 3D Model (STEP, Version K)

Additional Information:

Product Line Information

Related Products:

? Tooling

List all Documents

Product Features

(Please use the Product Drawing for all design activity)

Product Type Features:

- ? Insertion Force = Zero
- ? Number of Positions = 479? PCB Mount Style = Surface Mount
- ? <u>Grid Size</u> = 26x26
- Grid Spacing (mm [in]) = 1.27 x 1.27 [.050 x .050]
- ? Chip Compatibility = Intel ® Pentium ® 4 (mPGA479M pattern)
- ? Frame Style = Open
- ? Heat Sink Attachment = Without
- ? ZIF Actuator = Screwdriver/Cam
- Profile = Low
- ? Cover Material = High Temperature Thermoplastic
- 2 Leg Style = Ball Grid Array (BGA)
- ? Comment = With mask tape 75 micro thick.; Sn/Ag/Cu solderballs.

Termination Related Features:

? Socket Identifier = mPGA479M

Body Related Features:

- Pick and Place Cover = Tape
- ? Cover Color = Black
- ? Socket Overall Height (mm [in]) = 3 [0.118]

Contact Related Features:

- ? Contact Style = Stamped + Formed
- ? Contact Material = Copper Alloy
- ? Contact Mating Area Plating = Gold (30)

Housing Related Features:

- ? Housing Color = Black
- Pousing Material = Thermoplastic High Temperature
- ? Housing Flammability Rating = UL 94V -0
- ? Housing Material Temperature = High

Industry Standards:

- RoHS/ELV Compliance = RoHS compliant, ELV compliant
- ? <u>Lead Free Solder Processes</u> = Reflow solder capable to 245°C
- RoHS/ELV Compliance History = Always was RoHS compliant

Operation/Application:

? Application = Production

Packaging Related Features:

- Packaging Method = JEDEC Hard Tray
- ? Packaging Quantity = 600 sockets/box

Other:

? Brand = AMP